

## ABSTRACT

5           A die mold machine for molding a plurality of semiconductor assemblies  
on multiple substrate/leadframes includes a plurality of die mold layers stacked  
vertically one above the other to form a plurality of die mold sections. The top die  
mold layer has at least one aperture or die hall in the top most die layer and  
apertures or die halls in the in-between layers for passing molding compound  
which flows through the die hall in the top layer down through the die halls or  
10       apertures between the die mold layers into the die mold sections for molding  
semiconductor assemblies on said substrate/leadframes between said die mold  
layers.